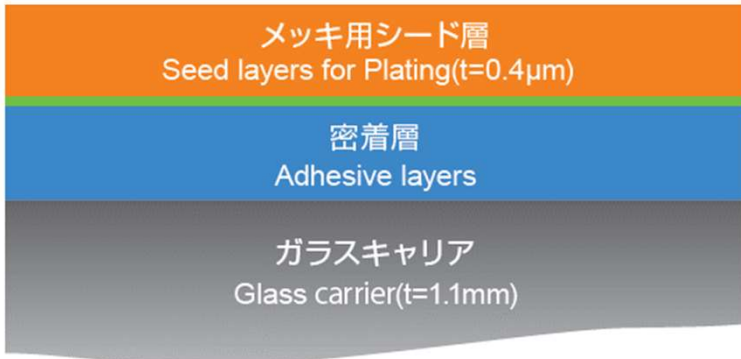


HRDP® (High Resolution De-bondable Panel)

Special glass carrier with quick mechanical de-bonding function suited for the RDL first process by ultra-fine circuits with thin RDL thickness with multiple layers.



剥離機能層
Release layer



Exterior Surface of HRDP®

HRDP® Features

- Ultra flatness in the size of panel.
- High-temperature de-bondable.
- Good uniformity of ultra-thin seed layer.

Application example

HRDP® technology for RDL※ first process.

※RDL : Redistribution layer

